HM5164405F Series
HM5165405F Series

64 M EDO DRAM (16-Mword × 4-bit)
8 k Refresh/4 k Refresh

ELPIDA

E0097H10 (1st edition)
(Previous ADE-203-1056C (Z))
Jan. 31, 2001

EOL Product

Description

The HM5164405F Series, HM5165405F Series are 64M-bit dynamic RAMs organized as 16,777,216-word × 4-bit. They have realized high performance and low power by employing CMOS process technology. HM5164405F Series, HM5165405F Series offer Extended Data Out (EDO) Page Mode as a high speed access mode. They have the package variation of standard 32-pin plastic SOJ and standard 32-pin plastic TSOPII.

Features

- Single 3.3 V supply: 3.3 V ± 0.3 V
- Access time: 50 ns/60 ns (max)
- Power dissipation
  - Active: 396 mW/360 mW (max) (HM5164405F Series)
    : 468 mW/396 mW (max) (HM5165405F Series)
  - Standby : 1.8 mW (max) (CMOS interface)
    : 1.1 mW (max) (L-version)
- EDO page mode capability
- Refresh cycles
  - $\overline{\text{RAS}}$-only refresh
    8192 cycles/64 ms (HM5164405F, HM5164405FL)
    4096 cycles/64 ms (HM5165405F, HM5165405FL)
  - CBR/Hidden refresh
    4096 cycles/64 ms (HM5164405F, HM5164405FL, HM5165405F, HM5165405FL)

This product became EOL in December, 2006.

Elpida Memory, Inc. is a joint venture DRAM company of NEC Corporation and Hitachi, Ltd.

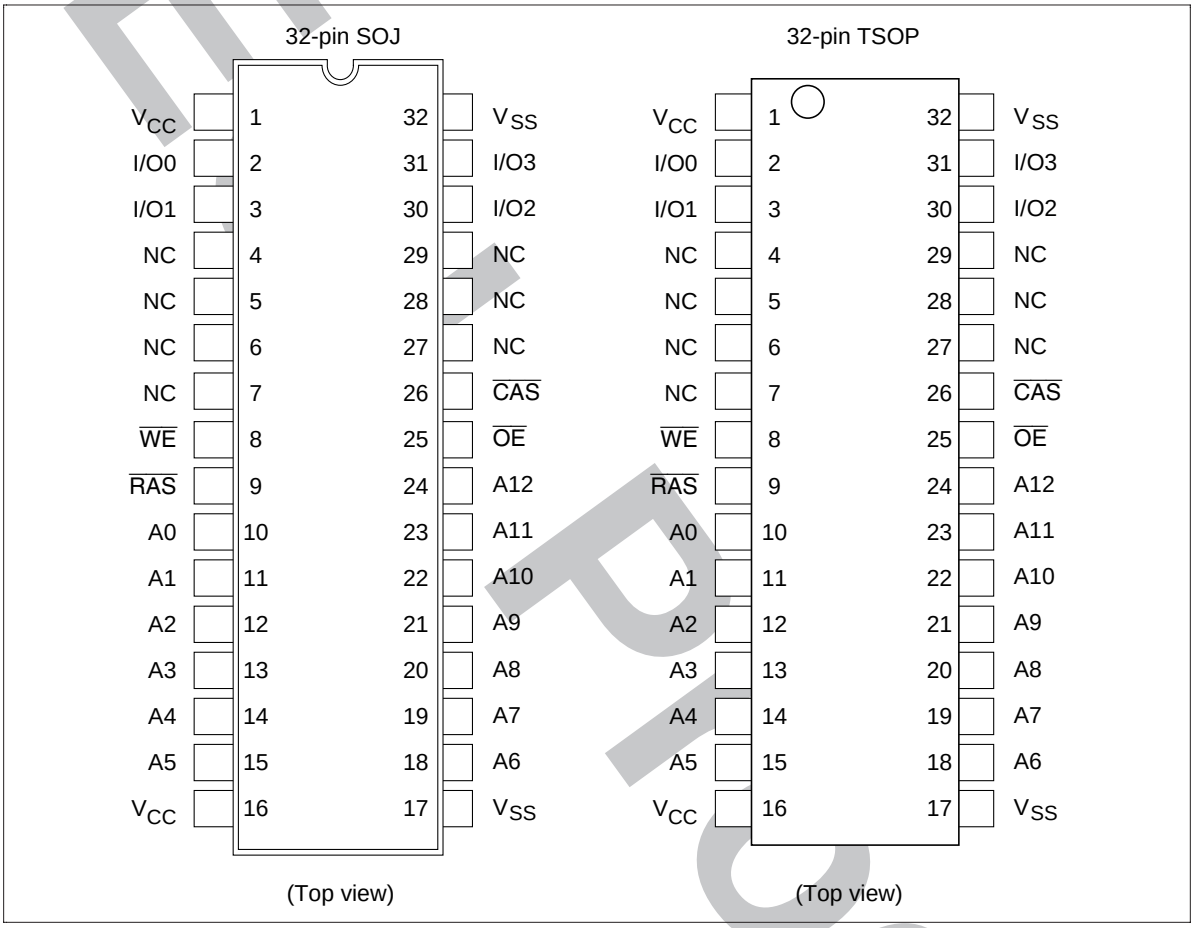
- 4 variations of refresh
  - — $\overline{\text{RAS}}$-only refresh
  - — $\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh
  - — Hidden refresh
  - — Self refresh (L-version)
- Battery backup operation (L-version)

Ordering Information

Type No.	Access time	Package
HM5164405FJ-5	50 ns	400-mil 32-pin plastic SOJ (CP-32DC)
HM5164405FJ-6	60 ns	
HM5164405FLJ-5	50 ns	
HM5164405FLJ-6	60 ns	
HM5165405FJ-5	50 ns	
HM5165405FJ-6	60 ns	
HM5165405FLJ-5	50 ns	
HM5165405FLJ-6	60 ns	
HM5164405FTT-5	50 ns	400-mil 32-pin plastic TSOP II (TTP-32DC)
HM5164405FTT-6	60 ns	
HM5164405FLTT-5	50 ns	
HM5164405FLTT-6	60 ns	
HM5165405FTT-5	50 ns	
HM5165405FTT-6	60 ns	
HM5165405FLTT-5	50 ns	
HM5165405FLTT-6	60 ns	

EOL Product

Pin Arrangement (HM5164405F Series)

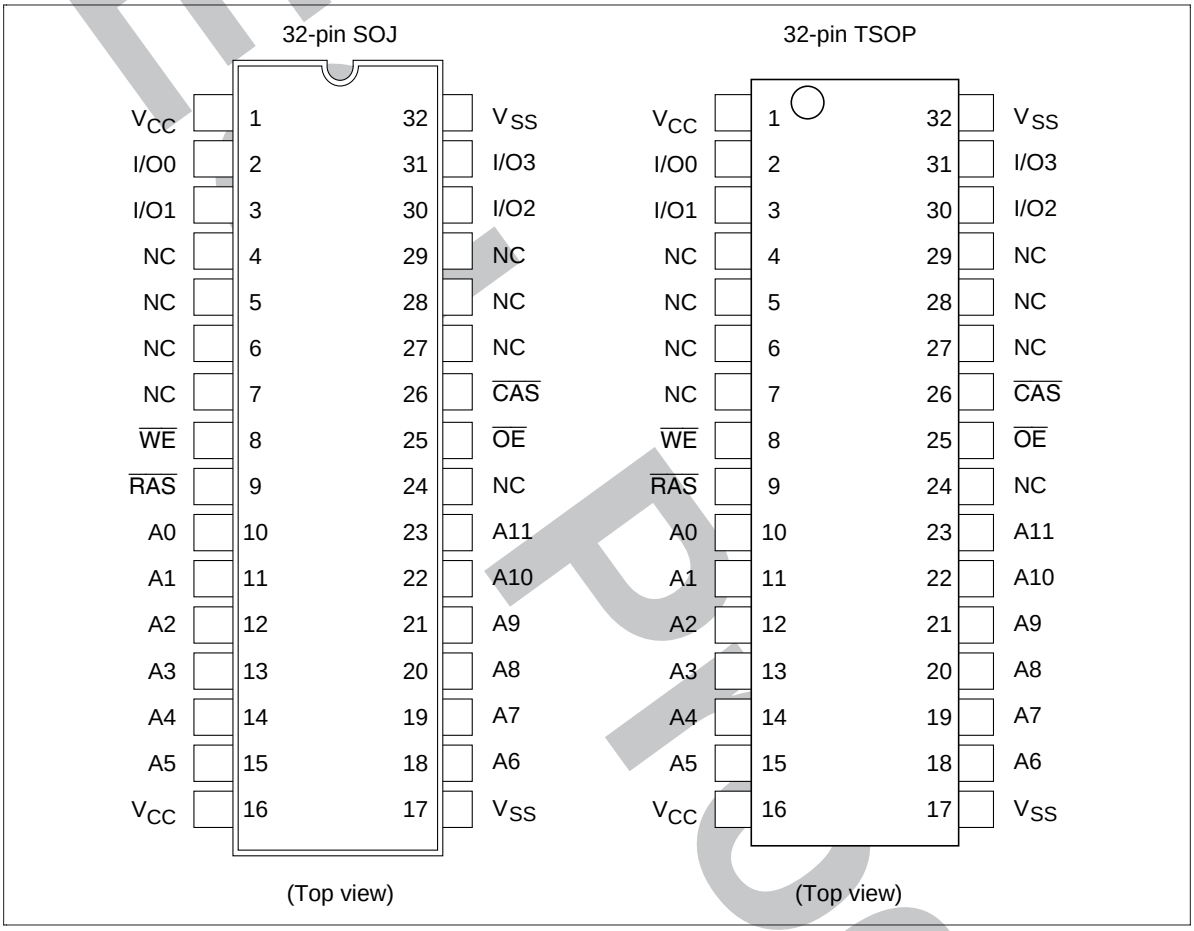


Pin Description

Pin name	Function
A0 to A12	Address input — Row/Refresh address A0 to A12 — Column address A0 to A10
I/O0 to I/O3	Data input/output
$\overline{RAS}$	Row address strobe
$\overline{CAS}$	Column address strobe
$\overline{WE}$	Write enable
$\overline{OE}$	Output enable
V_{CC}	Power supply
V_{SS}	Ground
NC	No connection

E Product

Pin Arrangement (HM5165405F Series)

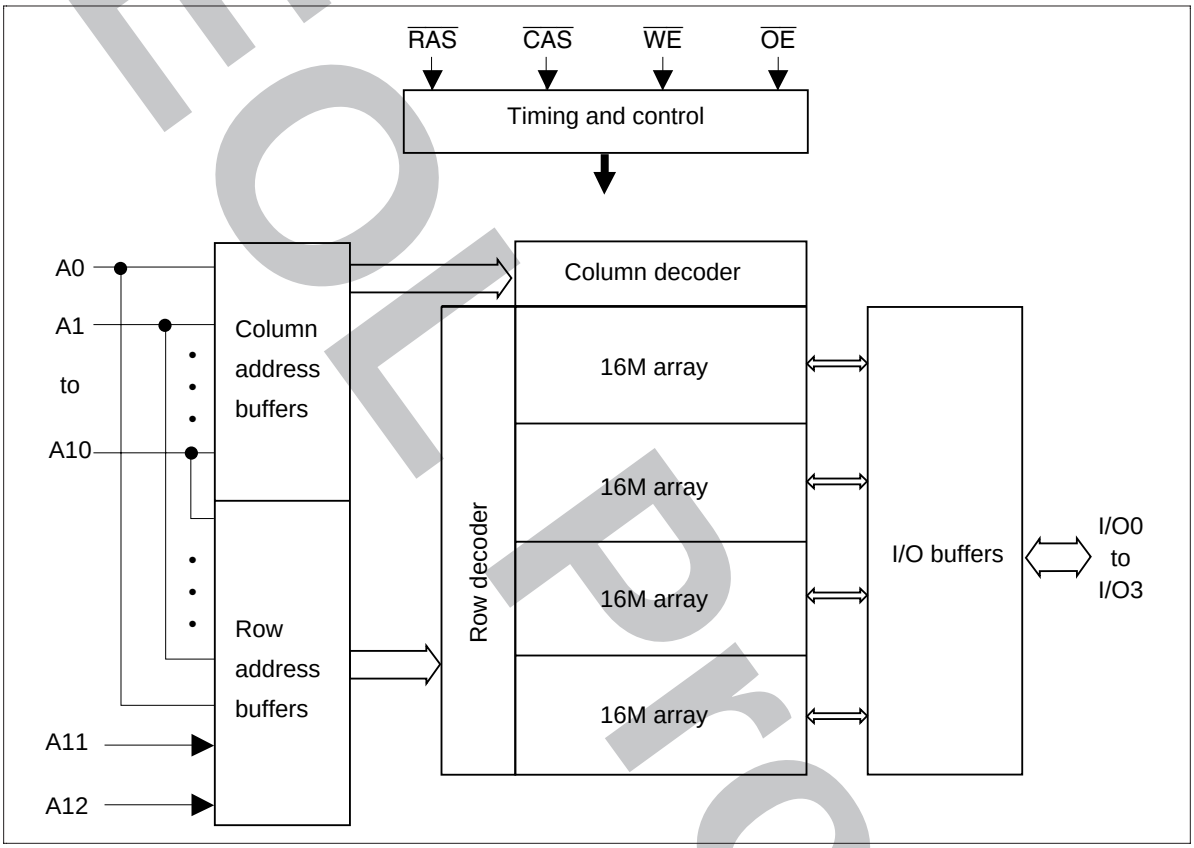


Pin Description

Pin name	Function
A0 to A11	Address input — Row/Refresh address A0 to A11 — Column address A0 to A11
I/O0 to I/O3	Data input/output
$\overline{RAS}$	Row address strobe
$\overline{CAS}$	Column address strobe
$\overline{WE}$	Write enable
$\overline{OE}$	Output enable
V_{CC}	Power supply
V_{SS}	Ground
NC	No connection

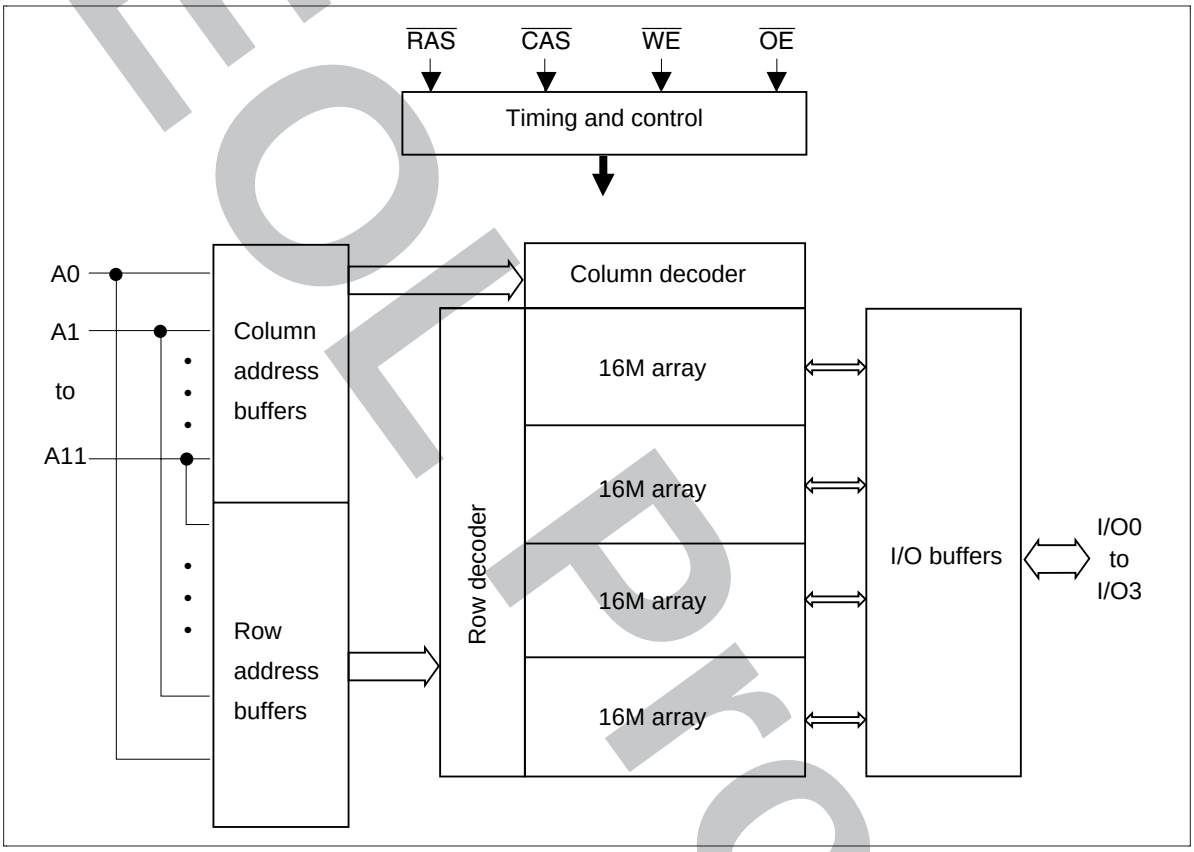
E Product

Block Diagram (HM5164405F Series)



EOL Product

Block Diagram (HM5165405F Series)



EOL Product

Operation Table

$\overline{RAS}$	$\overline{CAS}$	$\overline{WE}$	$\overline{OE}$	I/O 0 to I/O 3	Operation
H	×	×	×	High-Z	Standby
L	L	H	L	Dout	Read cycle
L	L	L*2	×	Din	Early write cycle
L	L	L*2	H	Din	Delayed write cycle
L	L	H to L	L to H	Dout/Din	Read-modify-write cycle
L	H	×	×	High-Z	$\overline{RAS}$-only refresh cycle
H to L	L	H	×	High-Z	$\overline{CAS}$-before-$\overline{RAS}$ refresh cycle or Self refresh cycle (L-version)
L	L	H	H	High-Z	Read cycle (Output disabled)

Notes: 1. H: V_{IH} (inactive), L: V_{IL} (active), ×: V_{IH} or V_{IL}
2. $t_{WCS} \geq 0$ ns: Early write cycle
$t_{WCS} < 0$ ns: Delayed write cycle

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Terminal voltage on any pin relative to V_{SS}	V_T	–0.5 to V_{CC} + 0.5 (≤ 4.6 V (max))	V
Power supply voltage relative to V_{SS}	V_{CC}	–0.5 to +4.6	V
Short circuit output current	Iout	50	mA
Power dissipation	P_T	1.0	W
Storage temperature	Tstg	–55 to +125	°C

DC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Supply voltage	V_{CC}	3.0	3.3	3.6	V	1, 2
	V_{SS}	0	0	0	V	2
Input high voltage	V_{IH}	2.0	—	V_{CC} + 0.3	V	1
Input low voltage	V_{IL}	–0.3	—	0.8	V	1
Ambient temperature range	Ta	0	—	70	˚C	

Notes: 1. All voltage referred to V_{SS}.
2. The supply voltage with all V_{CC} pins must be on the same level. The supply voltage with all V_{SS} pins must be on the same level.

EOL Product

DC Characteristics (HM5164405F Series)

		HM5164405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Test conditions
Operating current*1, *2	I_{CC1}	—	110	—	100	mA	t_{RC} = min
Standby current	I_{CC2}	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z
		—	0.5	—	0.5	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
Standby current (L-version)	I_{CC2}	—	300	—	300	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
$\overline{RAS}$-only refresh current*2	I_{CC3}	—	110	—	100	mA	t_{RC} = min
Standby current*1	I_{CC5}	—	5	—	5	mA	$\overline{RAS}$ = V_{IH}, $\overline{CAS}$ = V_{IL} Dout = enable
$\overline{CAS}$-before-$\overline{RAS}$ refresh current	I_{CC6}	—	110	—	100	mA	t_{RC} = min
EDO page mode current*1, *3	I_{CC7}	—	110	—	100	mA	$\overline{RAS}$ = V_{IL} , $\overline{CAS}$ cycle, t_{HPC} = t_{HPC} min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I_{CC10}	—	1.2	—	1.2	mA	CMOS interface Dout = High-Z CBR refresh: t_{RC} = 15.6 µs t_{RAS} ≤ 0.3 µs
Self refresh mode current (L-version)	I_{CC11}	—	500	—	500	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≤ 0.2 V Dout = High-Z
Input leakage current	I_{LI}	–5	5	–5	5	µA	0 V ≤ Vin ≤ V_{CC} + 0.3 V
Output leakage current	I_{LO}	–5	5	–5	5	µA	0 V ≤ Vout ≤ V_{CC} Dout = disable
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –2 mA
Output low voltage	V_{OL}	0	0.4	0	0.4	V	Low Iout = 2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.
2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Measured with one sequential address change per EDO cycle, t_{HPC}.
4. V_{IH} ≥ V_{CC} – 0.2 V, 0 V ≤ V_{IL} ≤ 0.2 V.

EOL Product

DC Characteristics (HM5165405F Series)

		HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Test conditions
Operating current*1, *2	I_{CC1}	—	130	—	110	mA	t_{RC} = min
Standby current	I_{CC2}	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z
		—	0.5	—	0.5	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
Standby current (L-version)	I_{CC2}	—	300	—	300	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
$\overline{RAS}$-only refresh current*2	I_{CC3}	—	130	—	110	mA	t_{RC} = min
Standby current*1	I_{CC5}	—	5	—	5	mA	$\overline{RAS}$ = V_{IH}, $\overline{CAS}$ = V_{IL} Dout = enable
$\overline{CAS}$-before-$\overline{RAS}$ refresh current	I_{CC6}	—	130	—	110	mA	t_{RC} = min
EDO page mode current*1, *3	I_{CC7}	—	110	—	100	mA	$\overline{RAS}$ = V_{IL} , $\overline{CAS}$ cycle, t_{HPC} = t_{HPC} min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I_{CC10}	—	1.2	—	1.2	mA	CMOS interface Dout = High-Z CBR refresh: t_{RC} = 15.6 µs t_{RAS} ≤ 0.3 µs
Self refresh mode current (L-version)	I_{CC11}	—	500	—	500	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≤ 0.2 V Dout = High-Z
Input leakage current	I_{LI}	–5	5	–5	5	µA	0 V ≤ Vin ≤ V_{CC} + 0.3 V
Output leakage current	I_{LO}	–5	5	–5	5	µA	0 V ≤ Vout ≤ V_{CC} Dout = disable
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –2 mA
Output low voltage	V_{OL}	0	0.4	0	0.4	V	Low Iout = 2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.
2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Measured with one sequential address change per EDO cycle, t_{HPC}.
4. V_{IH} ≥ V_{CC} – 0.2 V, 0 V ≤ V_{IL} ≤ 0.2 V.

EOL Product

Capacitance (Ta = 25˚C, V_{CC} = 3.3 V ± 0.3 V)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-in, Data-out)	$C_{I/O}$	—	7	pF	1, 2

Notes : 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
2. $\overline{RAS}$ and $\overline{CAS}$ = V_{IH} to disable Dout.

EOL Product

AC Characteristics (Ta = 0 to +70˚C, V_{CC} = 3.3 V ± 0.3 V, V_{SS} = 0 V) *1, *2, *19

Test Conditions

- Input rise and fall time: 2 ns
- Input pulse levels: V_{IL} = 0 V, V_{IH} = 3.0 V
- Input timing reference levels: 0.8 V, 2.0 V
- Output timing reference levels: 0.8 V, 2.0 V
- Output load: 1 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common parameters)

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t_{RC}	84	—	104	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	30	—	40	—	ns	
$\overline{CAS}$ precharge time	t_{CP}	8	—	10	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	50	10000	60	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	8	10000	10	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	ns	
Row address hold time	t_{RAH}	8	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	ns	
Column address hold time	t_{CAH}	8	—	10	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	12	37	14	45	ns	3
$\overline{RAS}$ to column address delay time	t_{RAD}	10	25	12	30	ns	4
$\overline{RAS}$ hold time	t_{RSH}	13	—	15	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	38	—	40	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	5	—	5	—	ns	
$\overline{OE}$ to Din delay time	t_{OED}	13	—	15	—	ns	5
$\overline{OE}$ delay time from Din	t_{DZO}	0	—	0	—	ns	6
$\overline{CAS}$ delay time from Din	t_{DZC}	0	—	0	—	ns	6
Transition time (rise and fall)	t_T	2	50	2	50	ns	7

EOL Product

Read Cycle

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Access time from $\overline{RAS}$	t_{RAC}	—	50	—	60	ns	8, 9
Access time from $\overline{CAS}$	t_{CAC}	—	13	—	15	ns	9, 10, 17
Access time from address	t_{AA}	—	25	—	30	ns	9, 11, 17
Access time from $\overline{OE}$	t_{OEA}	—	13	—	15	ns	9
Read command setup time	t_{RCS}	0	—	0	—	ns	
Read command hold time to $\overline{CAS}$	t_{RCH}	0	—	0	—	ns	12
Read command hold time from $\overline{RAS}$	t_{RCHR}	50	—	60	—	ns	
Read command hold time to $\overline{RAS}$	t_{RRH}	0	—	0	—	ns	12
Column address to $\overline{RAS}$ lead time	t_{RAL}	25	—	30	—	ns	
Column address to $\overline{CAS}$ lead time	t_{CAL}	15	—	18	—	ns	
$\overline{CAS}$ to output in low-Z	t_{CLZ}	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	ns	21
Output data hold time from $\overline{OE}$	t_{OHO}	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	13	—	15	ns	13, 21
Output buffer turn-off to $\overline{OE}$	t_{OEZ}	—	13	—	15	ns	13
$\overline{CAS}$ to Din delay time	t_{CDD}	13	—	15	—	ns	5
Output data hold time from $\overline{RAS}$	t_{OHR}	3	—	3	—	ns	21
Output buffer turn-off to $\overline{RAS}$	t_{OFR}	—	13	—	15	ns	13, 21
Output buffer turn-off to $\overline{WE}$	t_{WEZ}	—	13	—	15	ns	13
$\overline{WE}$ to Din delay time	t_{WED}	13	—	15	—	ns	
$\overline{RAS}$ to Din delay time	t_{RDD}	13	—	15	—	ns	

EOL Product

EOL Product

Write Cycle

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write command setup time	t_{WCS}	0	—	0	—	ns	14
Write command hold time	t_{WCH}	8	—	10	—	ns	
Write command pulse width	t_{WP}	8	—	10	—	ns	
Write command to $\overline{RAS}$ lead time	t_{RWL}	13	—	15	—	ns	
Write command to $\overline{CAS}$ lead time	t_{CWL}	8	—	10	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	ns	15
Data-in hold time	t_{DH}	8	—	10	—	ns	15

Read-Modify-Write Cycle

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read-modify-write cycle time	t_{RWC}	116	—	140	—	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	67	—	79	—	ns	14
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	30	—	34	—	ns	14
Column address to $\overline{WE}$ delay time	t_{AWD}	42	—	49	—	ns	14
$\overline{OE}$ hold time from $\overline{WE}$	t_{OEH}	13	—	15	—	ns	

Refresh Cycle

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
$\overline{CAS}$ setup time (CBR refresh cycle)	t_{CSR}	5	—	5	—	ns	
$\overline{CAS}$ hold time (CBR refresh cycle)	t_{CHR}	8	—	10	—	ns	
$\overline{WE}$ setup time (CBR refresh cycle)	t_{WRP}	0	—	0	—	ns	
$\overline{WE}$ hold time (CBR refresh cycle)	t_{WRH}	8	—	10	—	ns	
$\overline{RAS}$ precharge to $\overline{CAS}$ hold time	t_{RPC}	5	—	5	—	ns	

EDO Page Mode Cycle

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
EDO page mode cycle time	t_{HPC}	20	—	25	—	ns	20
EDO page mode $\overline{RAS}$ pulse width	t_{RASP}	—	100000	—	100000	ns	16
Access time from $\overline{CAS}$ precharge	t_{CPA}	—	28	—	35	ns	9, 17
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{CPRH}	28	—	35	—	ns	
Output data hold time from $\overline{CAS}$ low	t_{DOH}	3	—	3	—	ns	9, 22
$\overline{CAS}$ hold time referred $\overline{OE}$	t_{COL}	8	—	10	—	ns	
$\overline{CAS}$ to $\overline{OE}$ setup time	t_{COP}	5	—	5	—	ns	
Read command hold time from $\overline{CAS}$ precharge	t_{RCHC}	28	—	35	—	ns	
Write pulse width during $\overline{CAS}$ precharge	t_{WPE}	8	—	10	—	ns	
$\overline{OE}$ precharge time	t_{OEP}	8	—	10	—	ns	

EDO Page Mode Read-Modify-Write Cycle

		HM5164405F/HM5165405F					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
EDO page mode read-modify-write cycle time	t_{HPRWC}	57	—	68	—	ns	
$\overline{WE}$ delay time from $\overline{CAS}$ precharge	t_{CPW}	45	—	54	—	ns	14

Refresh (HM5164405F Series)

Parameter	Symbol	Max	Unit	Notes
Refresh period	t_{REF}	64	ms	8192 cycles

Refresh (HM5165405F Series)

Parameter	Symbol	Max	Unit	Notes
Refresh period	t_{REF}	64	ms	4096 cycles

EOL Product

Self Refresh Mode (L-version)

		HM5164405FL/HM5165405FL					
		-5		-6			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
$\overline{RAS}$ pulse width (self refresh)	t_{RASS}	100	—	100	—	µs	25
$\overline{RAS}$ precharge time (self refresh)	t_{RPS}	90	—	110	—	ns	25
$\overline{CAS}$ hold time (self refresh)	t_{CHS}	–50	—	–50	—	ns	

Notes:
1. AC measurements assume t_T = 2 ns.
2. An initial pause of 200 µs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{RAS}$-only refresh or $\overline{CAS}$-before-$\overline{RAS}$ refresh).
3. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, than the access time is controlled exclusively by t_{CAC}.
4. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.
5. Either t_{OED} or t_{CDD} must be satisfied.
6. Either t_{DZO} or t_{DZC} must be satisfied.
7. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
8. Assumes that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
9. Measured with a load circuit equivalent to 1 TTL loads and 100 pF.
10. Assumes that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\geq t_{RAD} + t_{AA}$ (max).
11. Assumes that $t_{RAD} \geq t_{RAD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\leq t_{RAD} + t_{AA}$ (max).
12. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
13. t_{OFF} (max), t_{OEZ} (max), t_{WEZ} (max) and t_{OFR} (max) define the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
14. t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}$ (min), $t_{CWD} \geq t_{CWD}$ (min), and $t_{AWD} \geq t_{AWD}$ (min), or $t_{CWD} \geq t_{CWD}$ (min), $t_{AWD} \geq t_{AWD}$ (min) and $t_{CPW} \geq t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
15. t_{DS} and t_{DH} are referred to $\overline{CAS}$ leading edge in early write cycles and to $\overline{WE}$ leading edge in delayed write or read-modify-write cycles.
16. t_{RASP} defines $\overline{RAS}$ pulse width in EDO page mode cycles.
17. Access time is determined by the longest among t_{AA}, t_{CAC} and t_{CPA}.
18. In delayed write or read-modify-write cycles, $\overline{OE}$ must disable output buffer prior to applying data to the device.
19. When output buffers are enabled once, sustain the low impedance state until valid data is obtained. When output buffer is turned on and off within a very short time, generally it causes large V_{CC}/V_{SS} line noise, which causes to degrade V_{IH} min/V_{IL} max level.

EO Product

20. t_{HPC} (min) can be achieved during a series of EDO page mode write cycles or EDO page mode read cycles. If both write and read operation are mixed in a EDO page mode $\overline{RAS}$ cycle (EDO page mode mix cycle (1), (2)), minimum value of $\overline{CAS}$ cycle ($t_{CAS} + t_{CP} + 2\ t_T$) becomes greater than the specified t_{HPC} (min) value. The value of $\overline{CAS}$ cycle time of mixed EDO page mode is shown in EDO page mode mix cycle (1) and (2).
21. Data output turns off and becomes high impedance from later rising edge of $\overline{RAS}$ and $\overline{CAS}$. Hold time and turn off time are specified by the timing specifications of later rising edge of $\overline{RAS}$ and $\overline{CAS}$ between t_{OHR} and t_{OH} and between t_{OFR} and t_{OFF}.
22. t_{DOH} defines the time at which the output level go cross. V_{OL} = 0.8 V, V_{OH} = 2.0 V of output timing reference level.
23. Before and after self refresh mode, execute CBR refresh to all refresh addresses in or within 64 ms period on the condition a and b below.
    a. Enter self refresh mode within 15.6 µs after either burst refresh or distributed refresh at equal interval to all refresh addresses are completed.
    b. Start burst refresh or distributed refresh at equal interval to all refresh addresses within 15.6µs after exiting from self refresh mode.
24. In case of entering from $\overline{RAS}$-only-refresh, it is necessary to execute CBR refresh before and after self refresh mode according as note 23.
25 At t_{RASS} > 100 µs, self refresh mode is activated, and not activated at t_{RASS} < 10 µs. It is undefined within the range of 10 µs ≤ t_{RASS} ≤ 100 µs. For t_{RASS} ≥ 10 µs, it is necessary to satisfy t_{RPS}.
26. XXX: H or L (H: V_{IH} (min) ≤ V_{IN} ≤ V_{IH} (max), L: V_{IL} (min) ≤ V_{IN} ≤ V_{IL} (max))

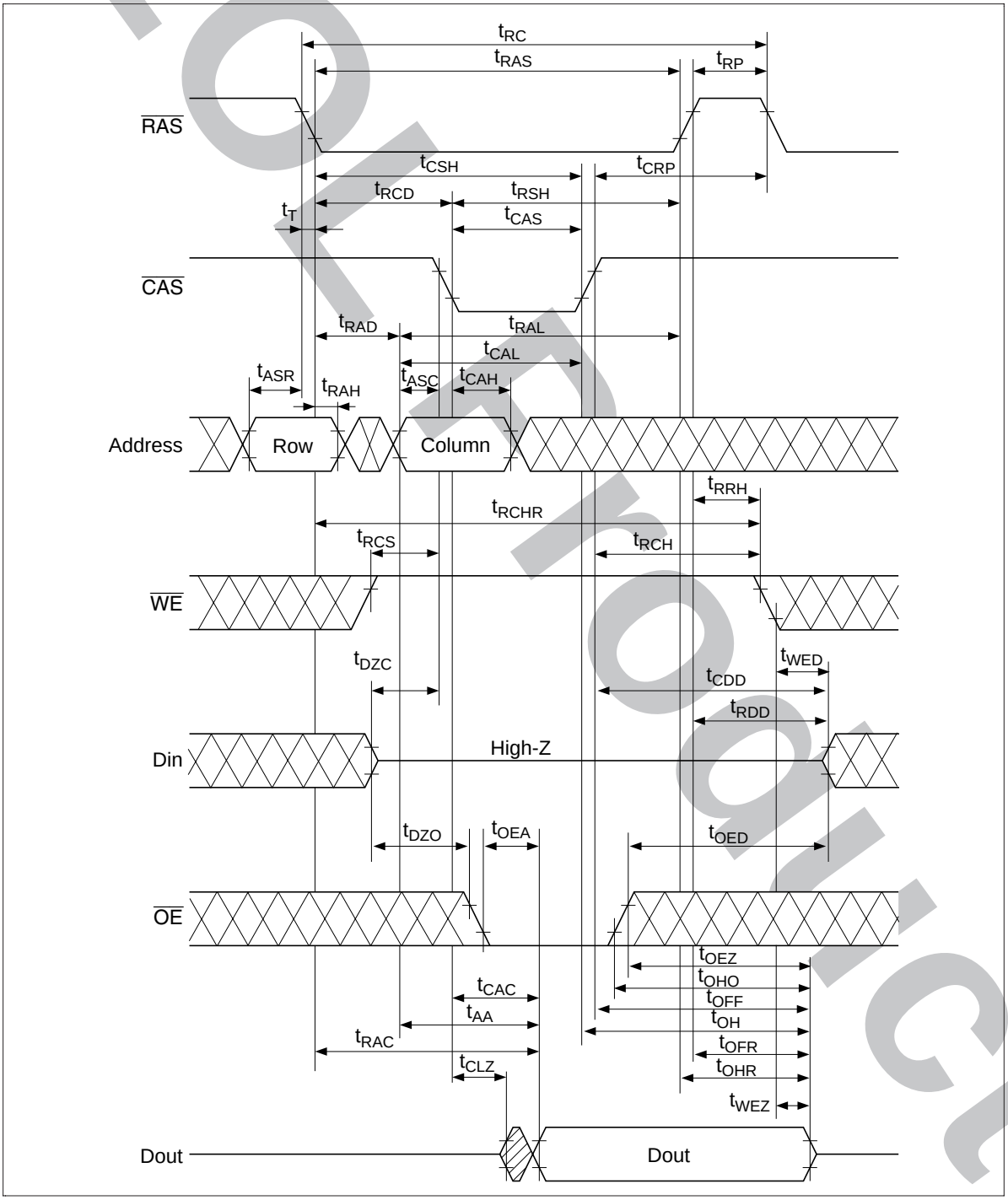
    ///////: Invalid Dout

    When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL}.

EOL Product

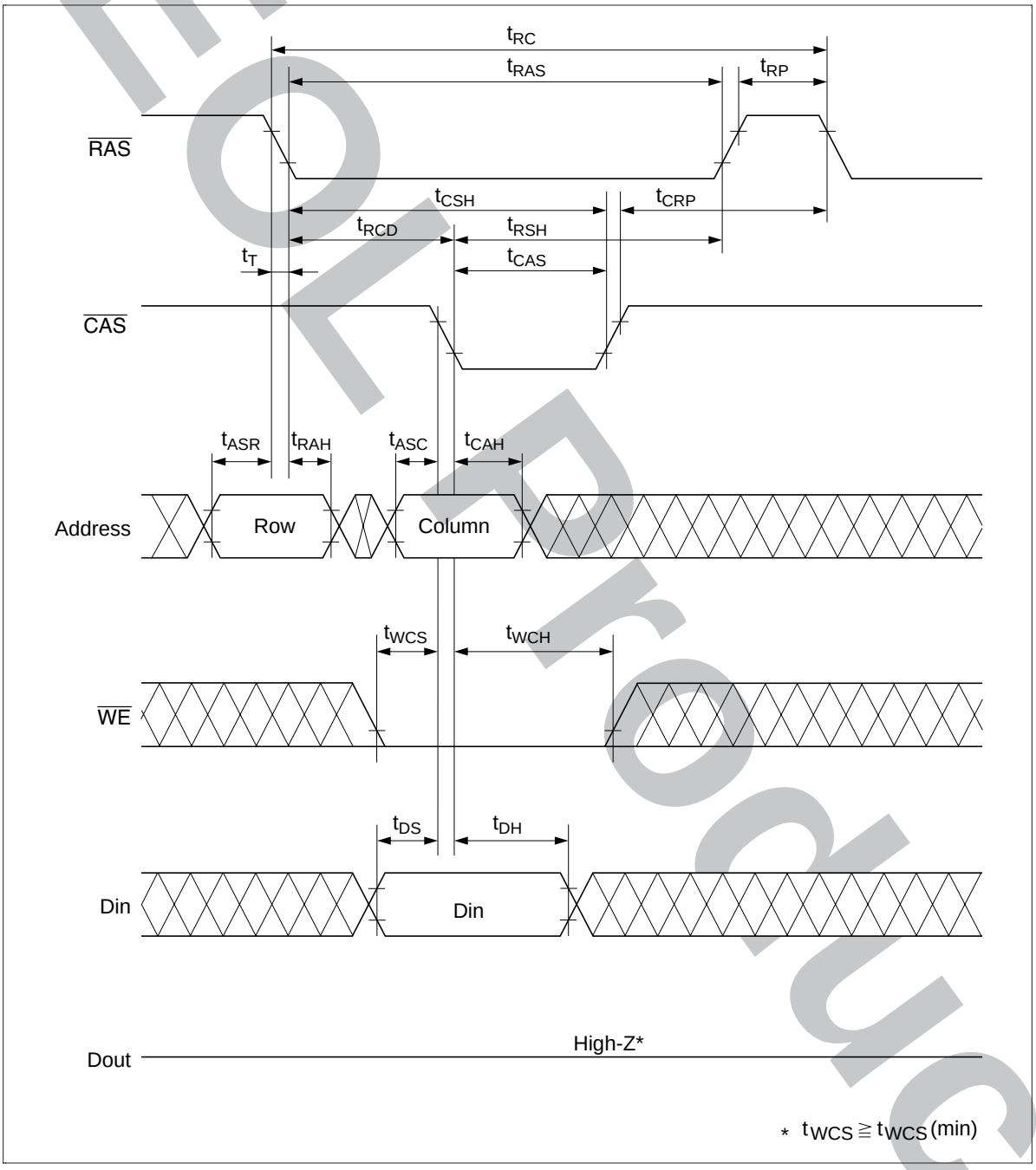
Timing Waveforms*[26]

Read Cycle



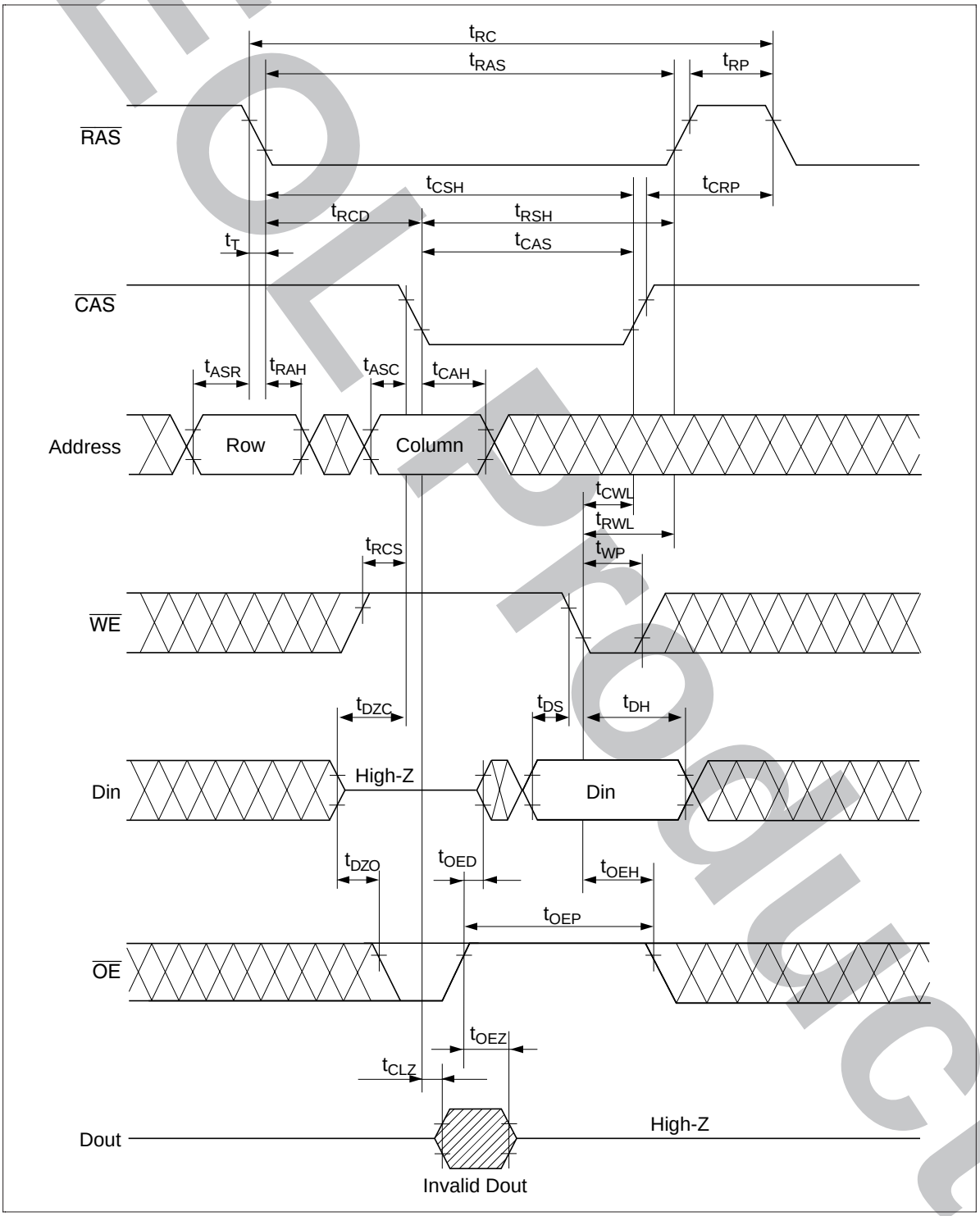
EOL Product

Early Write Cycle



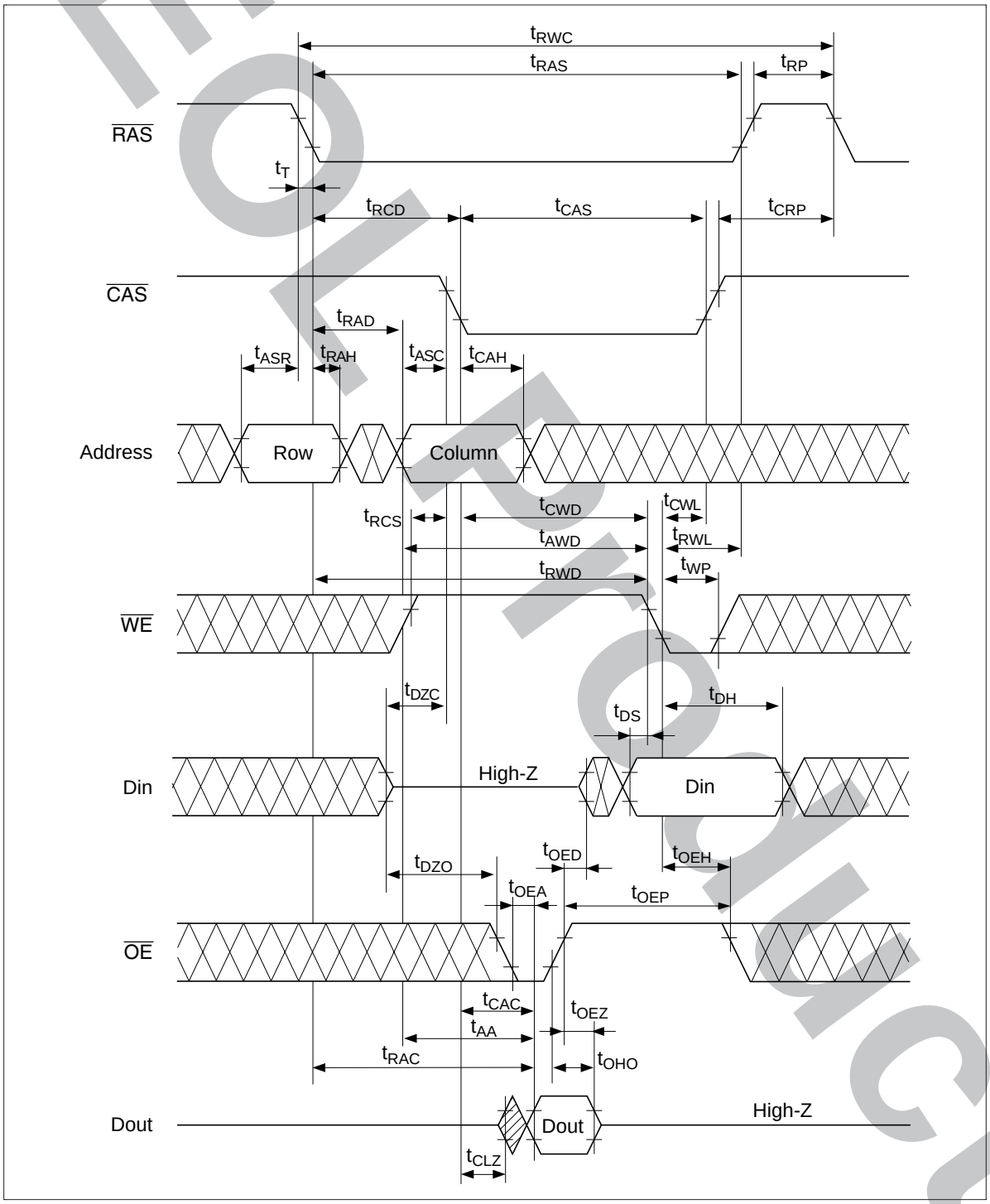
EOL Product

Delayed Write Cycle*[18]



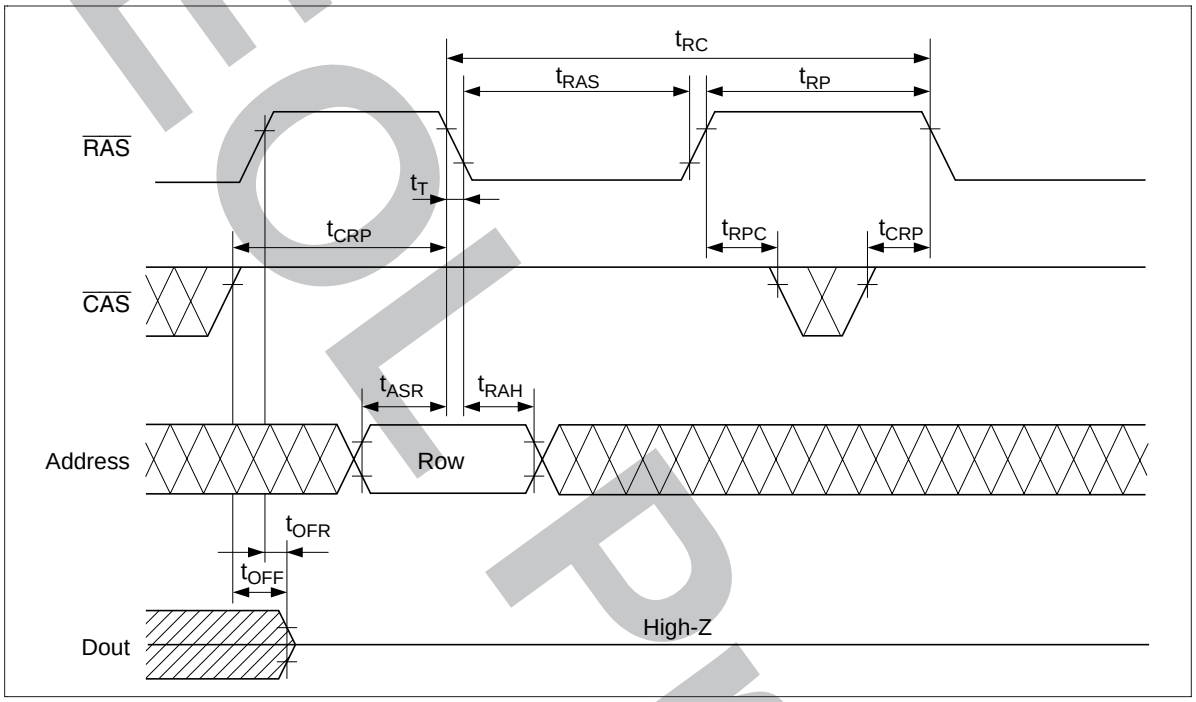
EOL Product

Read-Modify-Write Cycle*[18]



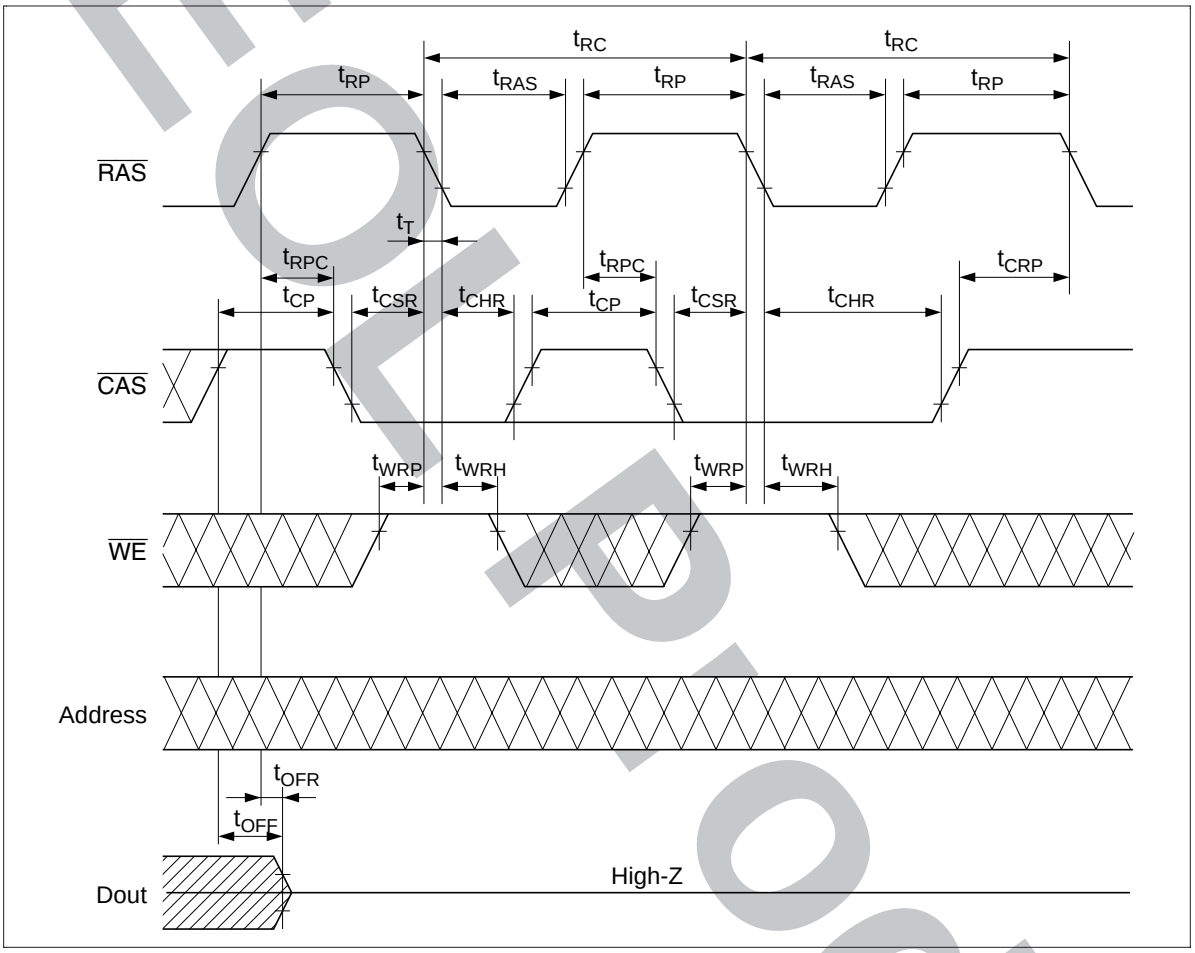
EOL Product

$\overline{\text{RAS}}$-Only Refresh Cycle



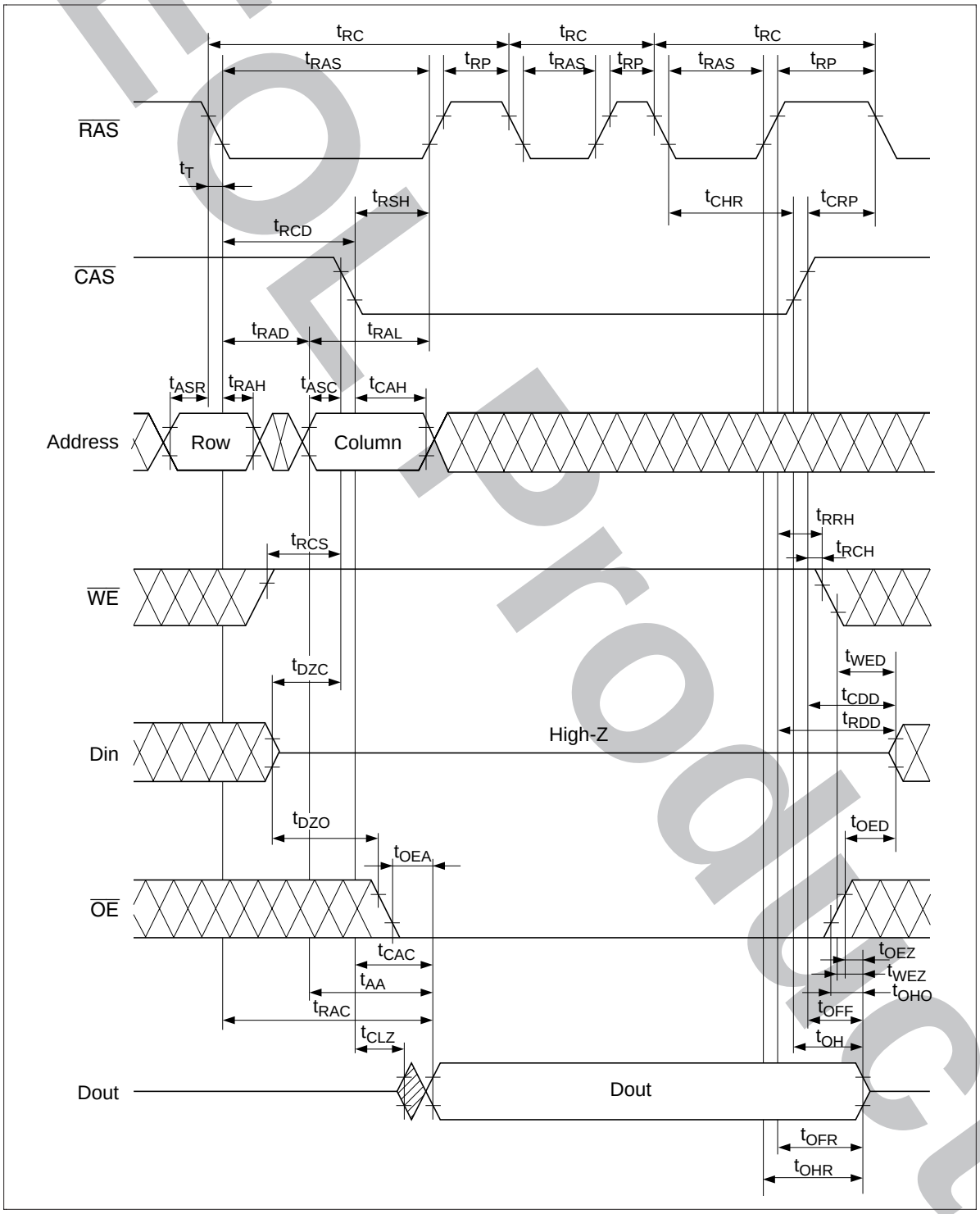
EOL Product

$\overline{\text{CAS}}$-Before-$\overline{\text{RAS}}$ Refresh Cycle



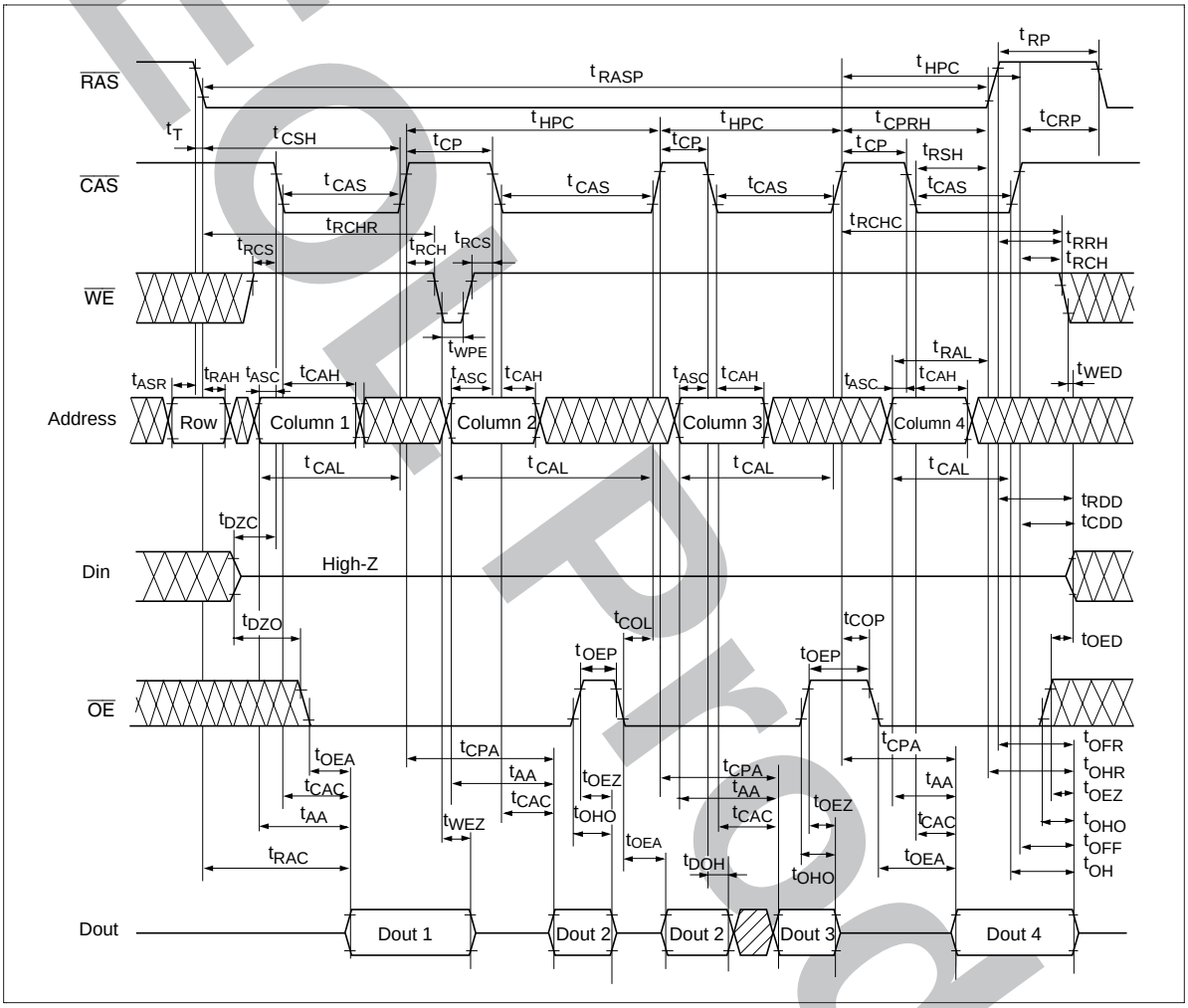
EOL Product

Hidden Refresh Cycle



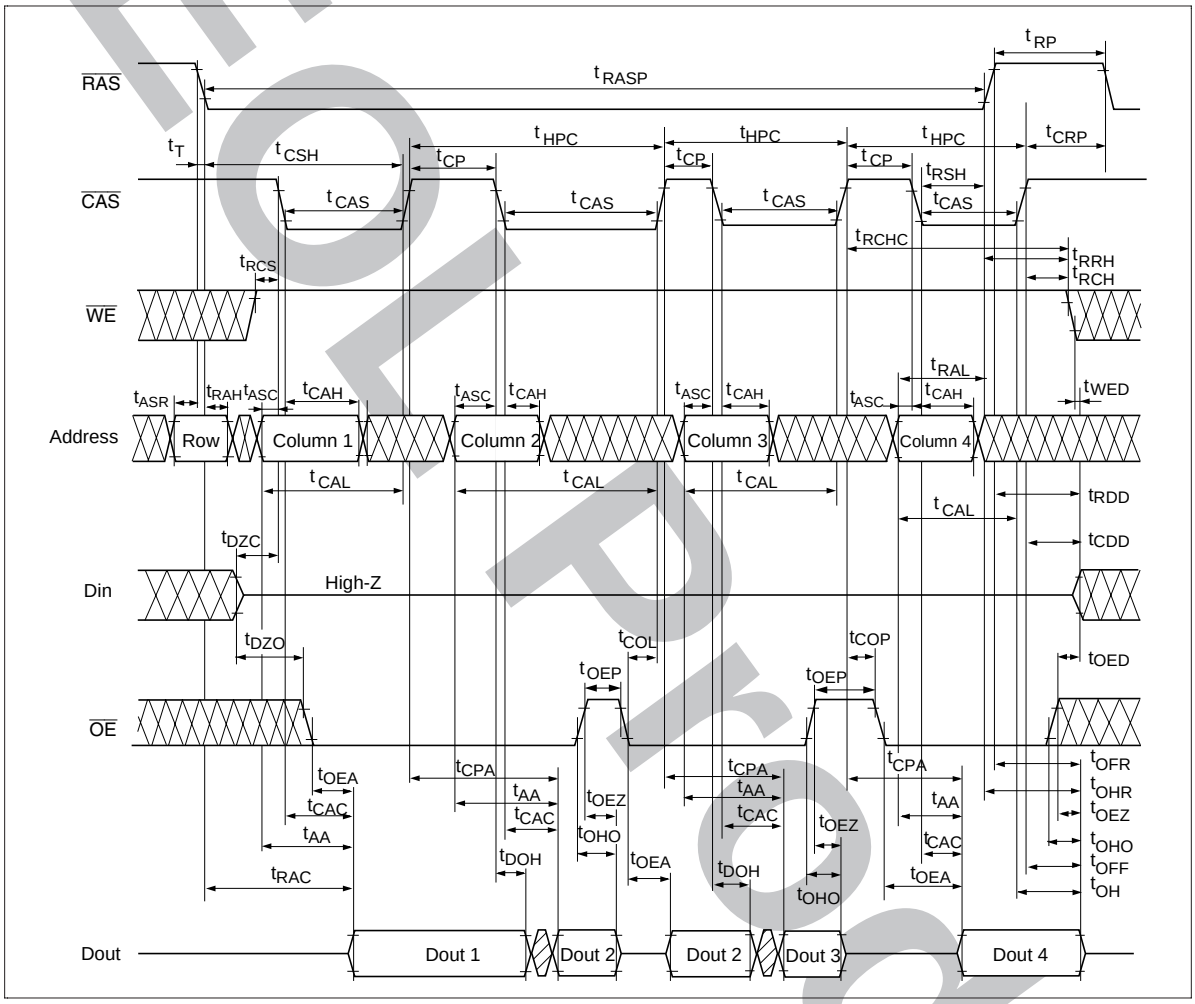
EOL Product

EDO Page Mode Read Cycle (1)



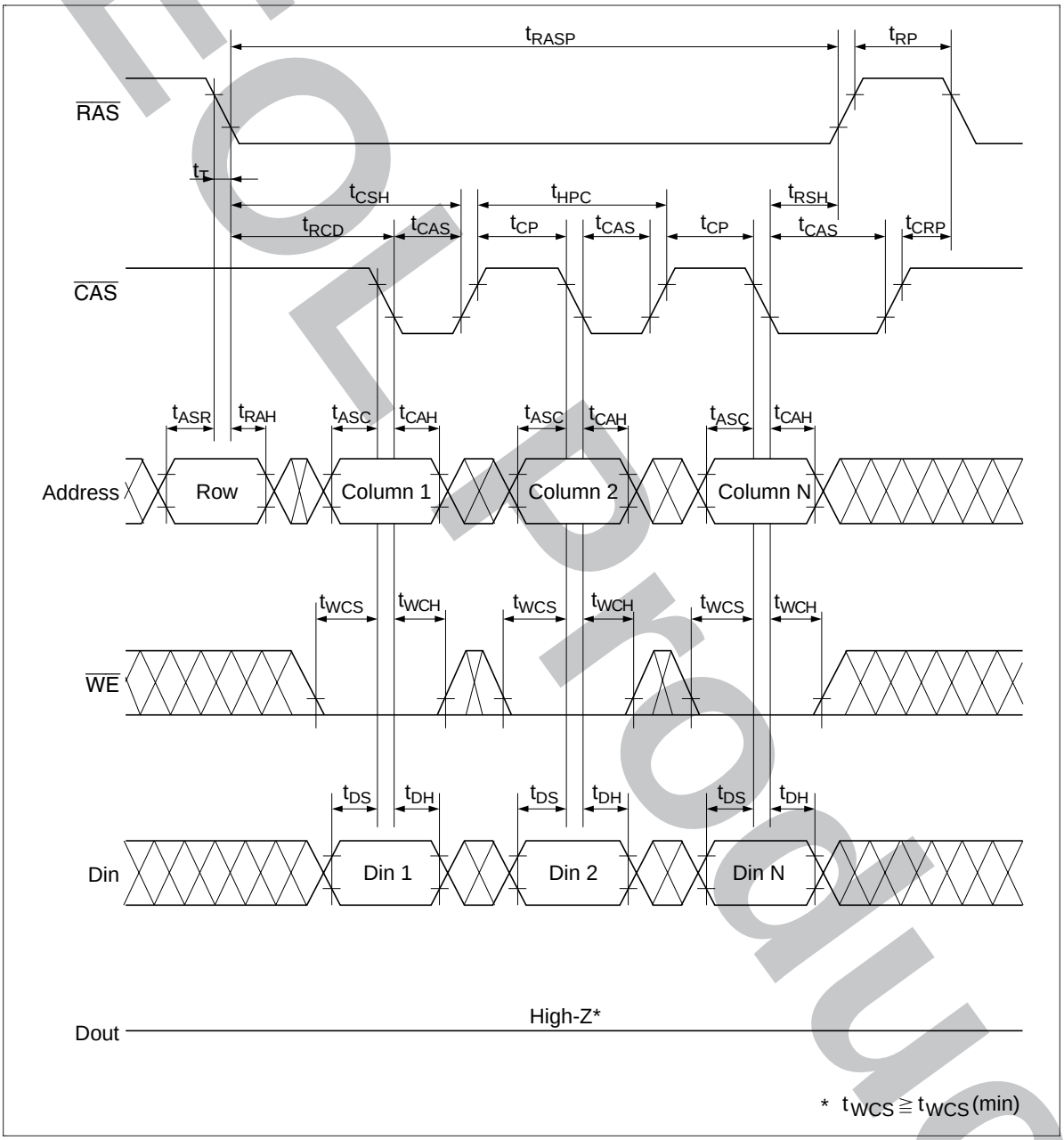
EOL Product

EDO Page Mode Read Cycle (2)



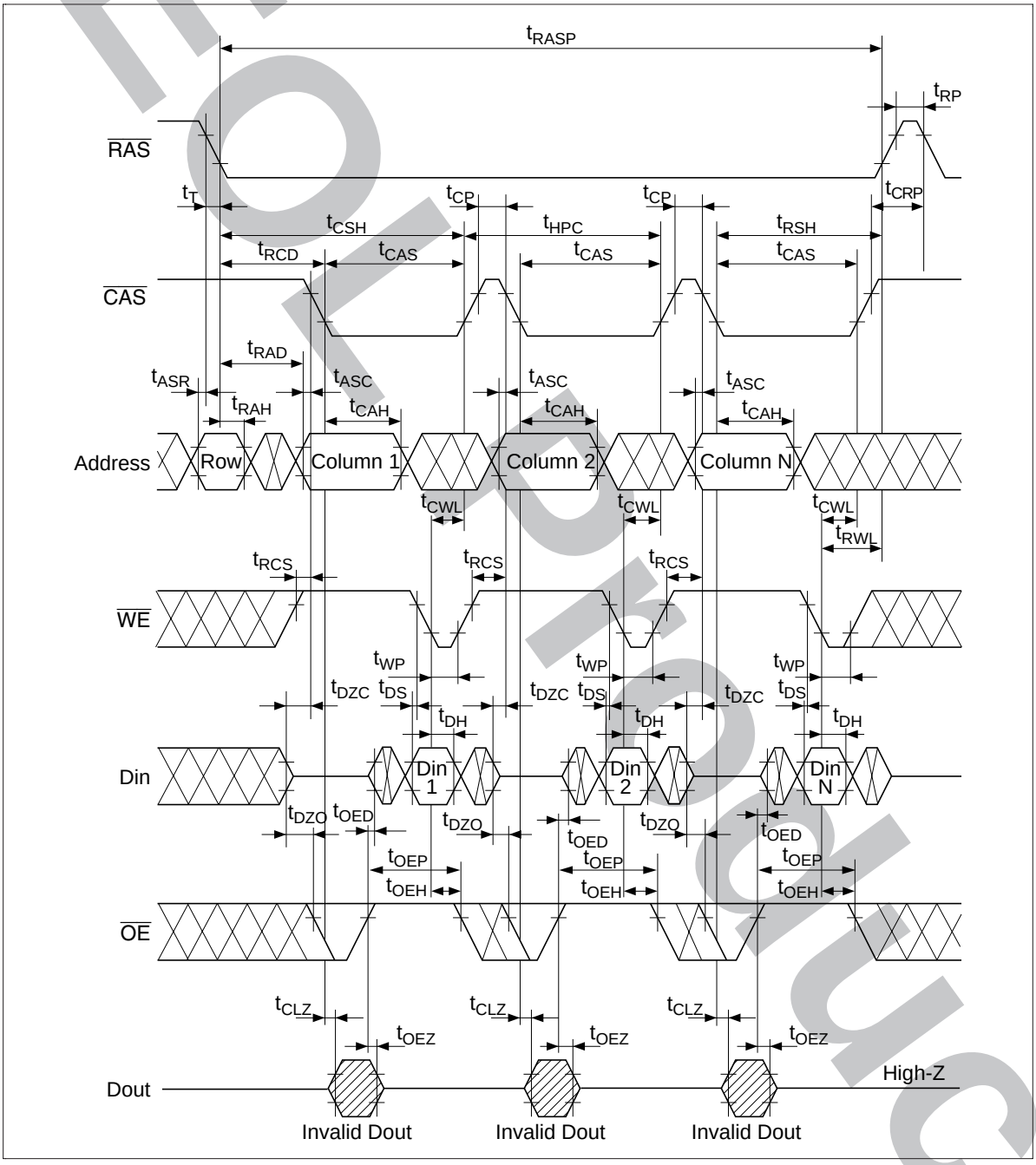
EOL Product

EDO Page Mode Early Write Cycle



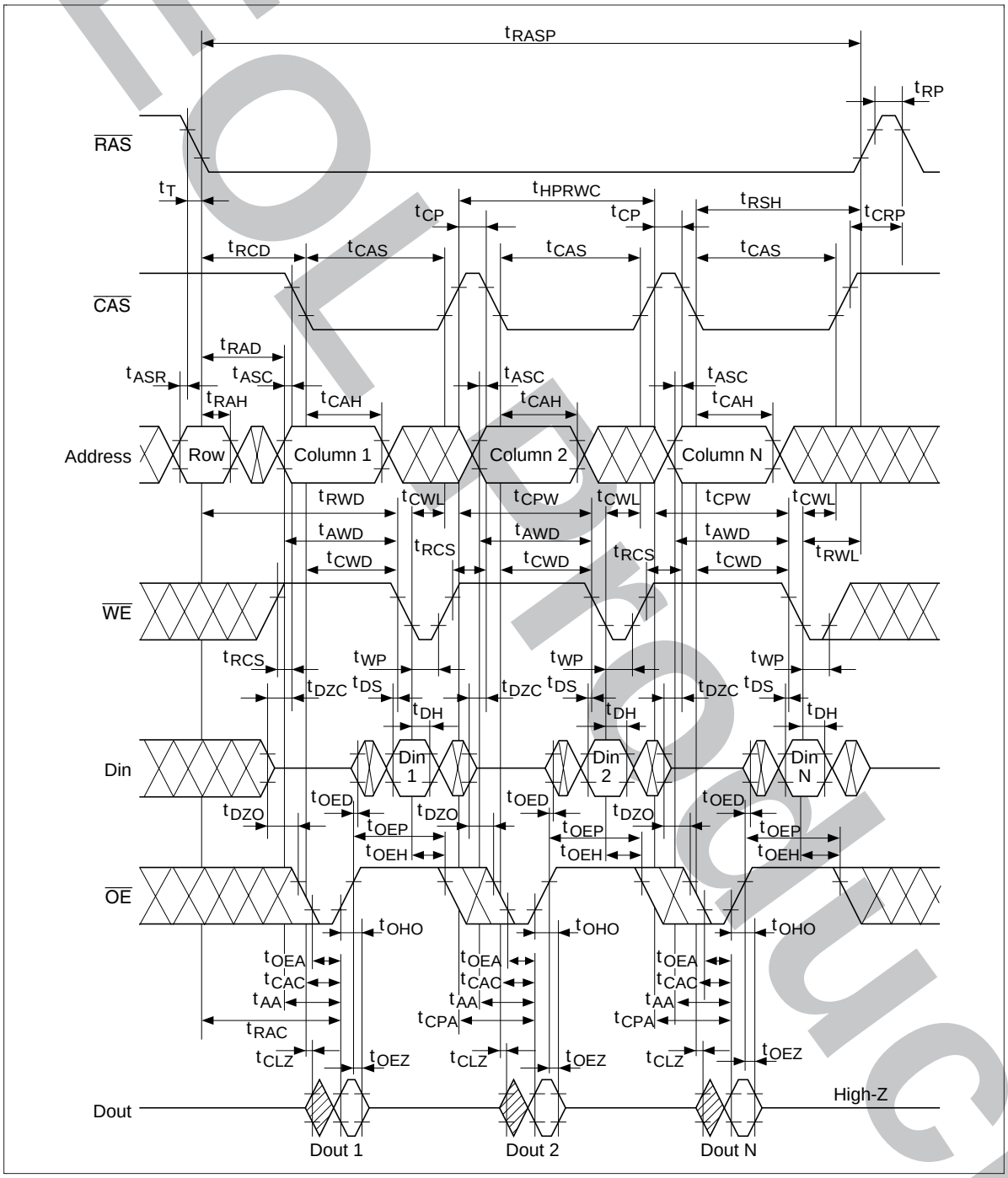
EOL Product

EDO Page Mode Delayed Write Cycle*[18]



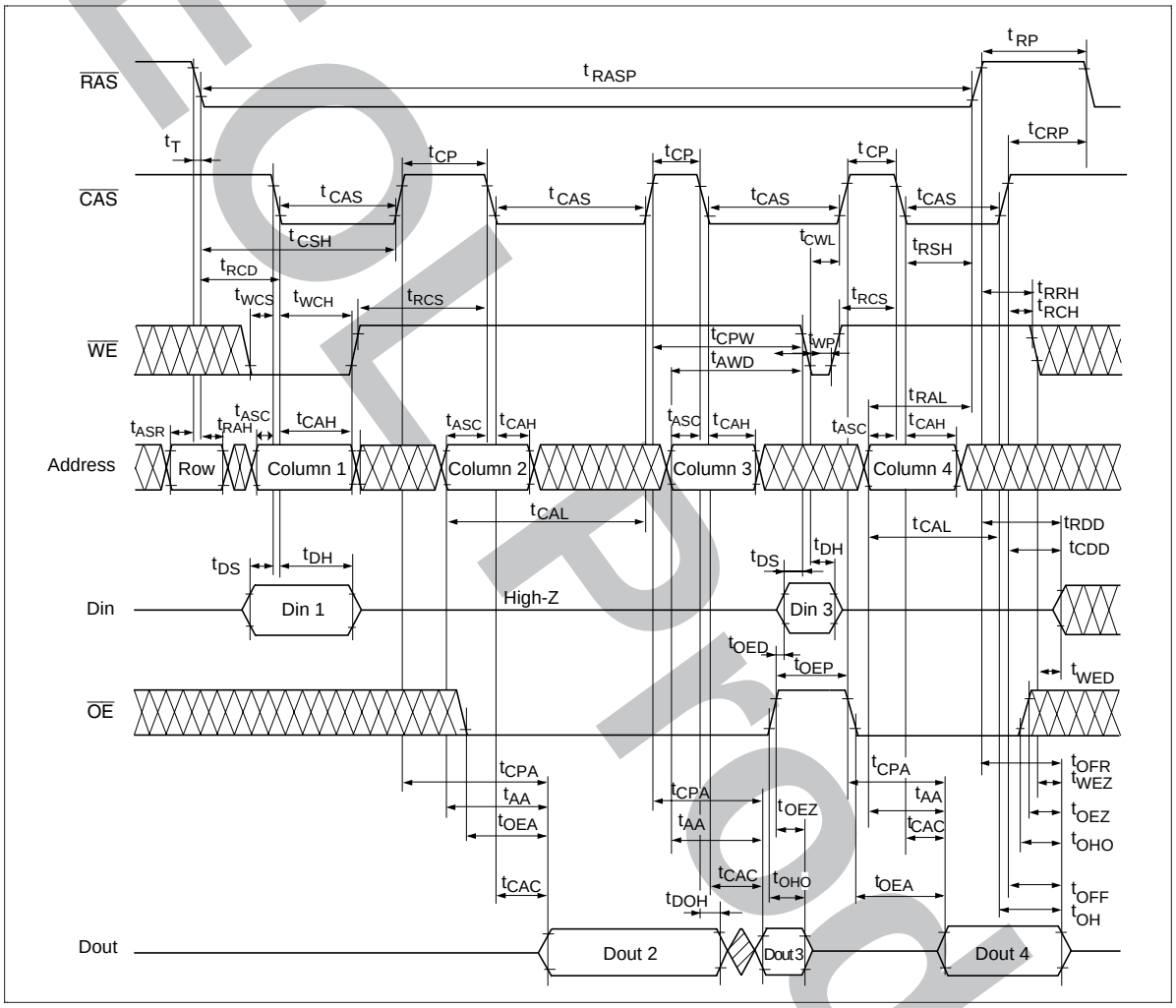
EOL Product

EDO Page Mode Read-Modify-Write Cycle*[18]



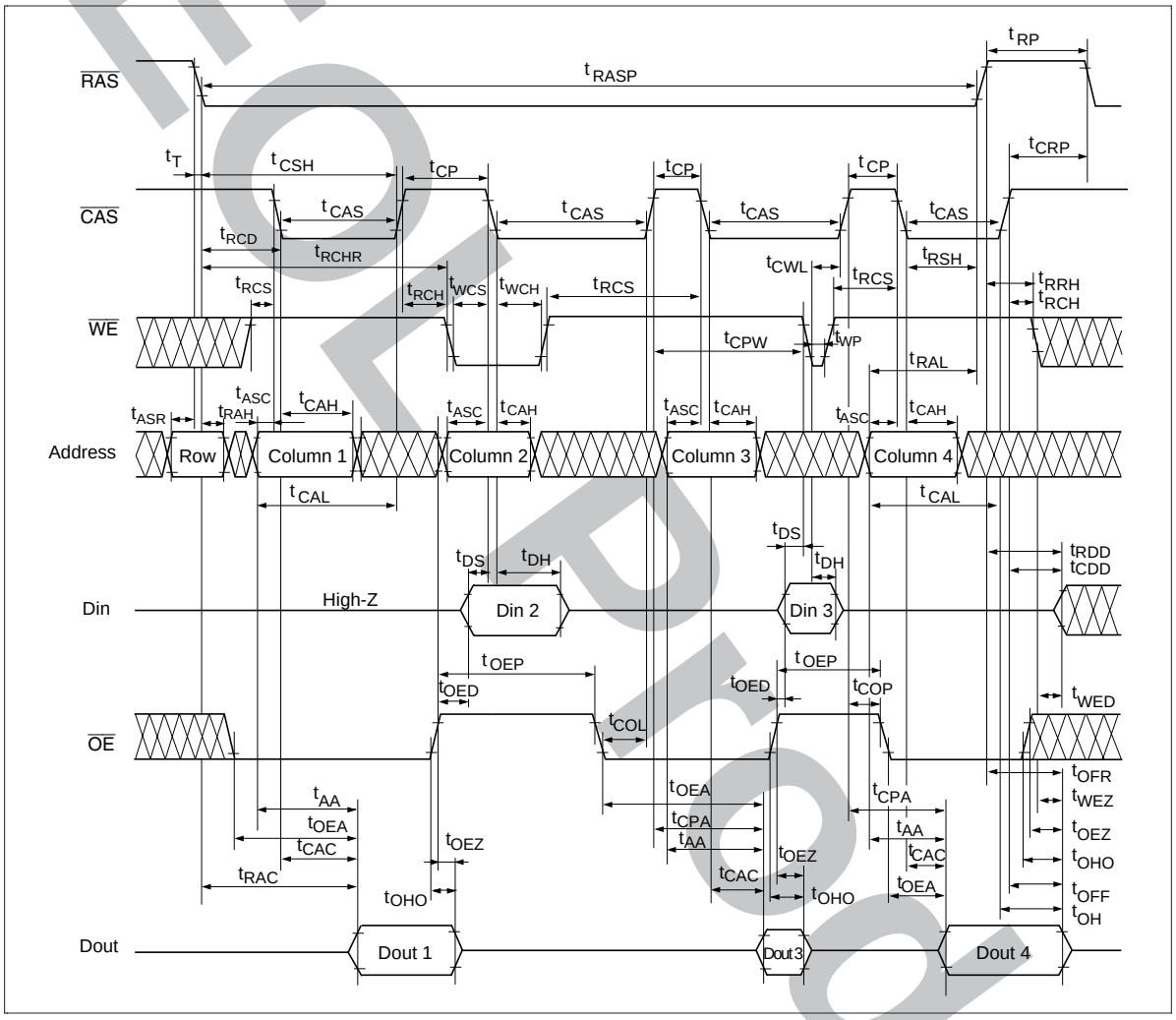
EOL Product

EDO Page Mode Mix Cycle (1)*[20]



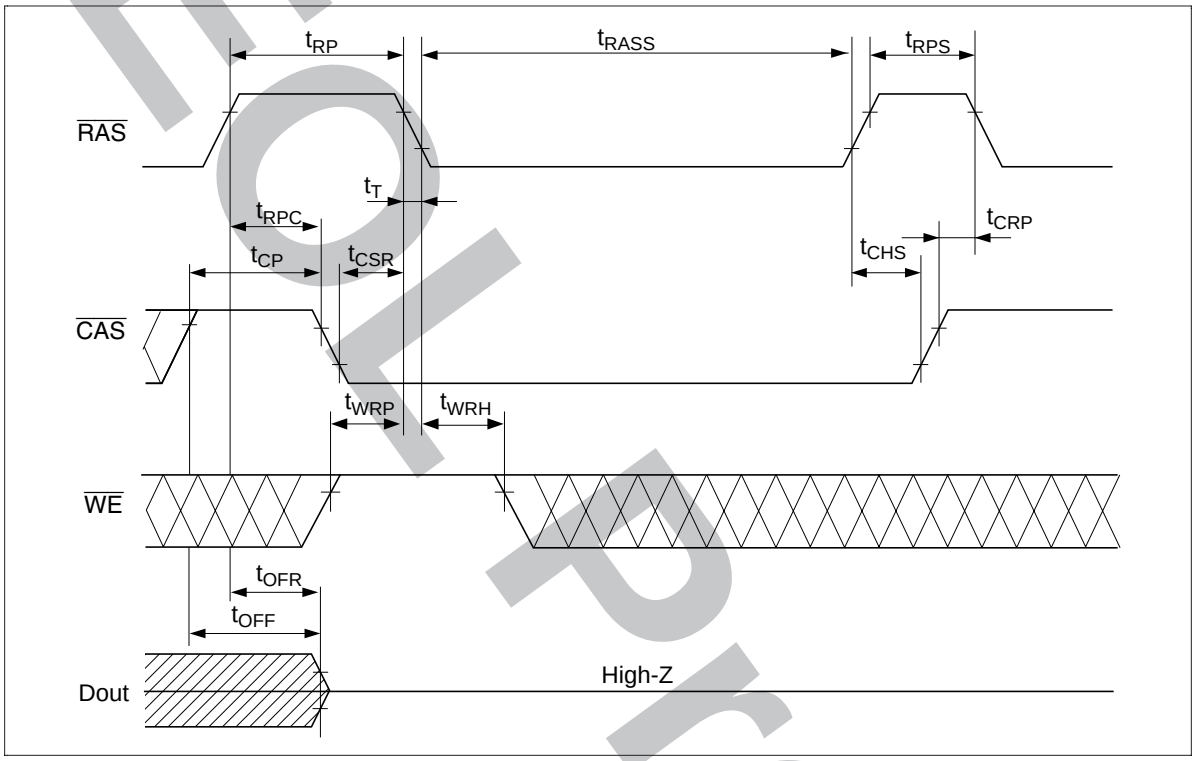
EOL Product

EDO Page Mode Mix Cycle (2) *[20]



EOL Product

Self Refresh Cycle (L-version)* [23, 24, 25]

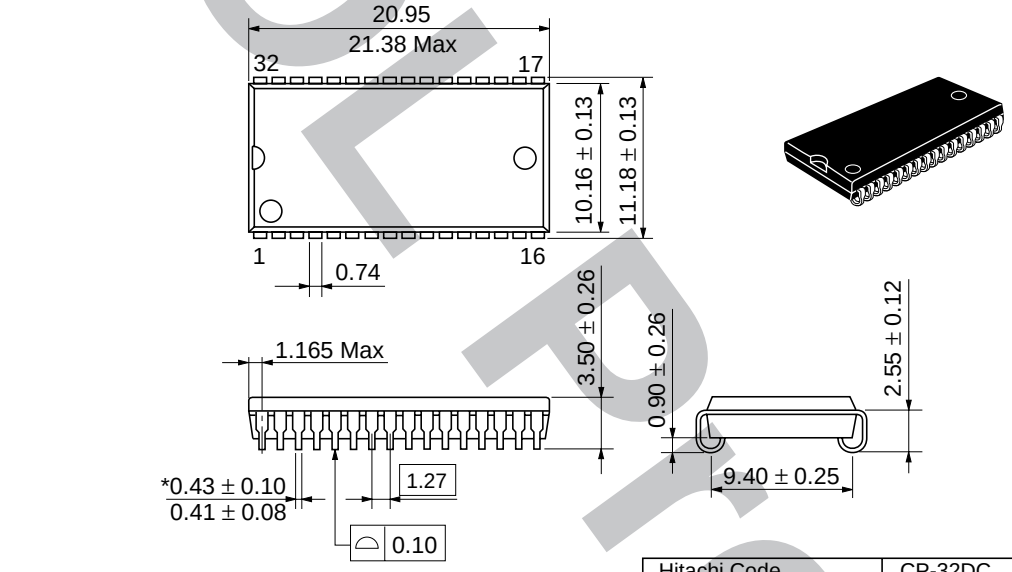


EOL Product

Package Dimensions

HM5164405FJ/FLJ Series
HM5165405FJ/FLJ Series (CP-32DC)

Unit: mm



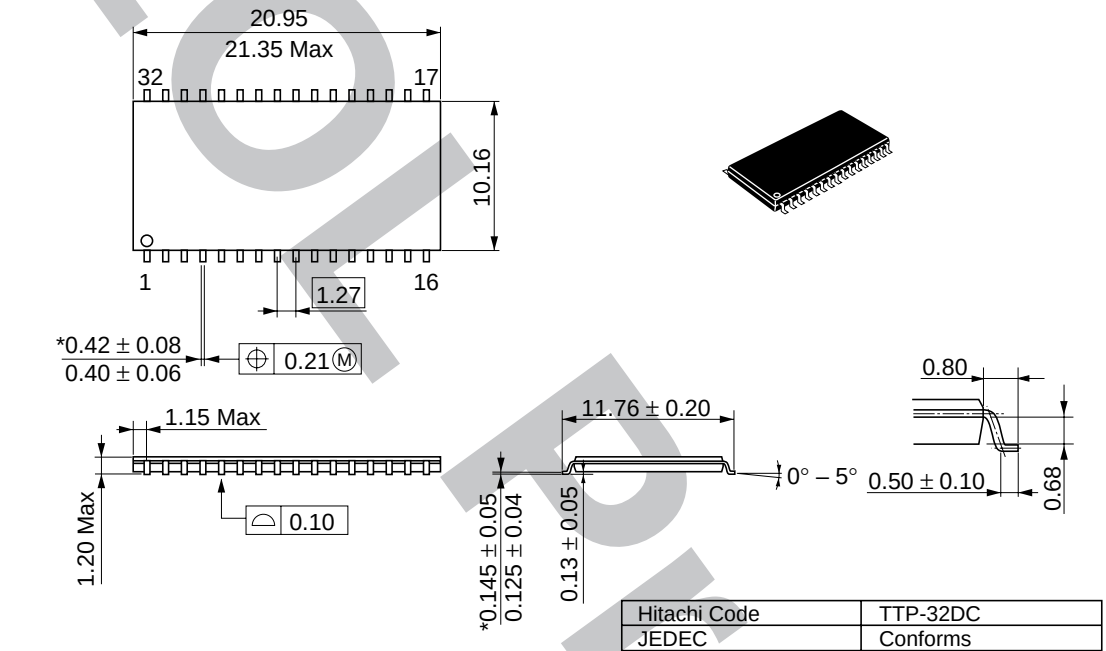
Hitachi Code	CP-32DC
JEDEC	—
EIAJ	Conforms
Weight (reference value)	1.2 g

*Dimension including the plating thickness
Base material dimension

EOL Product

HM5164405FTT/FLTT Series
HM5165405FTT/FLTT Series (TTP-32DC)

Unit: mm



Hitachi Code	TTP-32DC
JEDEC	Conforms
EIAJ	—
Weight (reference value)	0.51 g

*Dimension including the plating thickness
Base material dimension

EOL Product

Cautions

1. Elpida Memory, Inc. neither warrants nor grants licenses of any rights of Elpida Memory, Inc.'s or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Elpida Memory, Inc. bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
3. Elpida Memory, Inc. makes every attempt to ensure that its products are of high quality and reliability. However, contact Elpida Memory, Inc. before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
4. Design your application so that the product is used within the ranges guaranteed by Elpida Memory, Inc. particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Elpida Memory, Inc. bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as fail-safes, so that the equipment incorporating Elpida Memory, Inc. product does not cause bodily injury, fire or other consequential damage due to operation of the Elpida Memory, Inc. product.
5. This product is not designed to be radiation resistant.
6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Elpida Memory, Inc..
7. Contact Elpida Memory, Inc. for any questions regarding this document or Elpida Memory, Inc. semiconductor products.

© Elpida Memory, Inc. 2001

EOL Product